

TEMPERATURE CONTROL SYSTEM FOR A WORKPIECE CHUCK

Abstract of the Disclosure

A system for and method of controlling the temperature of a flat workpiece such as a semiconductor wafer are disclosed. The workpiece is mounted on a workpiece chuck which is mounted over a base between the chuck and a host machine such as a wafer prober used to test integrated circuits on a wafer. The chuck includes an upper portion on which the workpiece is mounted. The temperature of the upper portion of the chuck is controlled to control the temperature of the workpiece. The temperature of the base is controlled to reduce the amount of heat flow between the chuck and the host machine. A power and control system includes a switching power supply which provides power to system components including heaters in the chuck used to heat the workpiece. A series of filters removes electrical noise generated by the switching power supply such that low-noise operation is realized.

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